NOTES (UNLESS OTHERWISE SPECIFIED): 1) PCB IS 7-LAYER, .062" THICK. 2) CONSTRUCTION IS SOLDER-MASK-OVER-BARE-COPPER (SMOBC). 3) ACCEPTABLITY SHALL BE BASED ON IPC-A-600, CLASS 2. 4) THE FOLLOWING GERBER RS274X PHOTO TOOL FILES SHALL BE USED TO DEFINE ALL CIRCUIT FEATURES: *.GTL - TOP LAYER GERBER DATA *.G1 - MID LAYER 1 GERBER DATA : -*.GP1 — INTERNAL PLANE LAYER 1 GERBER DATA *.GP2 — INTERNAL PLANE LAYER 2 GERBER DATA *.GP3— INTERNAL PLANE LAYER 3 GERBER DATA *.GP4 — INTERNAL PLANE LAYER 4 GERBER DATA *.GBL = BOTTOM LAYER GERBER DATA *.GTO = TOP OVERLAY GERBER DATA *.GTS = TOP SOLDER MASK GERBER DATA *.GTP = TOP-SDE SOLDER PASTE MASK *GBO = BOTTOM OVERLAY GERBER DATA *.GBS = BOTTOM SOLDER MASK GERBER DATA *.GBP = BOTTOM-SIDE SOLDER PASTE MASK 1111 BRING TO ATTN OF ALEX CHANDY NOTE: SPECIAL INSTRUCTIONS FOR EDGE PLATING (2 PLCS) 5) THE PHOTO TOOL SHALL NOT BE COMPENSATED WITHOUT PRIOR ENGINEERING APPROVAL PCB DESIGNER: RICH LOBDLL PH (805) 880-1621 FAX (805) 961-1792. FABRICATION TOLERANCES 6) END PRODUCT CONDUCTOR WIDTHS AND PAD DIAMETERS SHALL NOT VARY MORE THAN 1,0002" FROM THE 1:1 DIMENSIONS OF THE MASTER ARTWORK. 7) THE CONDUCTIVE PATTERN SHALL BE POSITIONED SO THAT THE LOCATION OF ANY PAD OR LAND SHALL BE WITHIN LOOSE" DIAMETER TO THE TRUE POSITION OF THE HOLE IT CRCUMSCRIBES. 8) ALL DRILL HOLE SIZES AND TOLERANCES APPLY AFTER PLATING. 9) THE MINIMUM AINJULAR RING SHALL BE 0.005". 10) BOW AND TWIST SHALL NOT EXCEED 0.007" PER NICH. 11) FOR PCB ROUTING DIMENSIONS: JOXY = +/-.005" JOX = +/-.002" 11 Edge plate connected to layer #.GP4

FABRICATION TOLERANCES

MATERIAL

12) BASE MATERIAL IS FR4 EPOXY FIBERGLASS
13) SEE STACK-UP LEGEND FOR COPPER CLADDING CALL OUTS

GENERAL

PLATING 14) ALL HOLES AND CONDUCTIVE SURFACES SHALL BE PLATED WITH A MINIMUM OF 0.001" COPPER. 15) AFTER SOLDERMASK, ALL EXPOSIT HOLES AND CONDUCTIVE SURFACES SHALL BE COATED WITH A GOLD MINIFESION PLATING TO PRESERVE SOLDERABUTY.

16) COPPER THEVING ON LAYERS AS NEEDED

16a) NOTE EDGE PLATING CALLED OUT ON DRAWING 2 PLCS

COATINGS

17) THE SOLDERMASK SHALL BE BLACK LIQUID PHOTO-IMAGEABLE PER IPC-SM-840, TYPE-B, CLASS 2.
18) THE SOLDERMASK REGISTRATION ALLOWANCE IS 0.003".

MARKING

19) THE LEGEND SHALL BE SCREEN-PRINTED USING PERMANENT YELLOW EPOXY NK.
20) THE SCREEN PERNITHING REGISTRATION ALLOWANCE IS 0.007". THERE SHALL BE NO INK ON ANY
SOLDER PAD OR LAND.
21) THE YENDOR CODE AND UL FLAMMABILITY RATING MAY BE ETCHED IN THE FOL OR MARKED IN
PERMANENT EPOXY NK (VENDOR'S OPTION). ELECTRICAL TESTING

22) ALL BOARDS SHALL BE ELECTRICALLY TESTED TO THE SUPPLED PC-D-356A NET LIST FOR CONTINUITY, OPENS AND SHORTS.

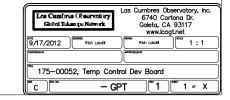
Layer Stack Up Detail for: 175-00052, rev1, Temp Controller Dev Board.PcbDoc Layer Name COPPER THICKNESS Top Layer (*.GTL) 1/2 oz, 1 oz Finished Multi-Net(*.GP1) 1 oz Mid-Layer (*.G1) 1 oz AGND (*.GP2) 1 oz Multi-Net (*.GP3) 1 oz DGND (*.GP4) 1 oz Bottom Layer (*.GBL) 1/2 oz, 1 oz Finished

PRIMARY PCB SPECIFICATIONS
(REFER TO COMPLETE SPEC LISTING AT LEFT FOR FURTHER DETAILS)

NUMBER OF LAYERS — FINISHED THICKNESS — .062" BASE MATERIAL FR4 PLATING TYPE - GOLD IMMERSION

BLACK

SOLDER MASK COLOR -



DIBODES A PROPRETARY DESIGN OWNED BY LAS CLARERES IT IS SUBMITTED FOR A SPECIFIC PURPOSE UNDER A CON-DIDISING, AND EXCEPT FOR PURPOSES EXPRESSLY GRAVIED